



M/S AF  
25611-000029/US

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Cheol Joon YOO                      Conf. No.: 4604  
Serial No.: 10/029,165                      Group: 1722  
Filed: December 20, 2001                      Examiner: R. B. Davis  
For: CLEANER FOR MOLDING APPARATUS OF SEMICONDUCTOR  
CHIP PACKAGES

June 10, 2004

**RESPONSE UNDER 37 C.F.R. § 1.116**

M/S AF  
Commissioner of Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Responsive to the Final Official Action ("Action") dated March 10, 2004, the following amendments and remarks are respectfully submitted in connection with the above-referenced application. The Applicant respectfully contends that the present amendments to the claims place them in better condition for appeal and/or in condition for allowance and respectfully requests, therefore, entry and consideration of the following amendments. The sections included in this response are as follows:

**Amendments to the Specification** begin on page 2;

**Amendments to the Claims** begin on page 3; and

**Remarks** begin on page 8 of this paper.

THE REMAINDER THIS PAGE HAS BEEN LEFT BLANK INTENTIONALLY

OK TO ENTER  
6/17/04 RP